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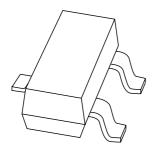
If you have any questions related to the data sheet, please contact our nearest sales office via e-mail or telephone (details via **salesaddresses@nexperia.com**). Thank you for your cooperation and understanding,

Kind regards,

Team Nexperia

# **DISCRETE SEMICONDUCTORS**

# DATA SHEET



# **BF840**NPN medium frequency transistor

Product data sheet Supersedes data of 1999 Apr 12 2004 Jan 13



NXP Semiconductors Product data sheet

# NPN medium frequency transistor

**BF840** 

#### **FEATURES**

- Low current (max. 25 mA)
- Low voltage (max. 40 V).

#### **APPLICATIONS**

- AM mixers
- IF amplifiers in AM/FM receivers.

#### **DESCRIPTION**

NPN medium frequency transistor in a SOT23 plastic package.

#### **MARKING**

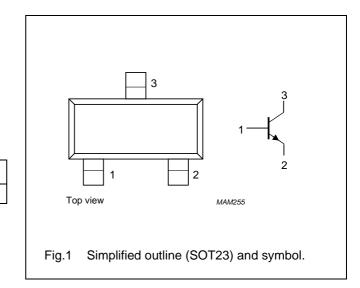
TYPE NUMBER	MARKING CODE(1)	
BF840	NC*	

#### Note

- 1. \* = p: Made in Hong Kong.
  - \* = t : Made in Malaysia.
  - \* = W : Made in China.

#### **PINNING**

PIN	DESCRIPTION	
1	base	
2	emitter	
3	collector	



#### **ORDERING INFORMATION**

TYPE		PACKAGE			
NUMBER	NAME	ME DESCRIPTION VERSION			
BF840	_	plastic surface mounted package; 3 leads SOT23			

#### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	40	V
V <sub>CEO</sub>	collector-emitter voltage	open base	_	40	V
V <sub>EBO</sub>	emitter-base voltage	open collector	_	4	V
I <sub>C</sub>	collector current (DC)		_	25	mA
I <sub>CM</sub>	peak collector current		_	25	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C; note 1	_	250	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T <sub>amb</sub>	operating ambient temperature		-65	+150	°C

#### Note

1. Transistor mounted on an FR4 printed-circuit board.

2004 Jan 13 2

NXP Semiconductors Product data sheet

# NPN medium frequency transistor

BF840

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	note 1	500	K/W

#### Note

1. Transistor mounted on an FR4 printed-circuit board.

#### **CHARACTERISTICS**

 $T_i = 25$  °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I <sub>CBO</sub>	collector cut-off current	I <sub>E</sub> = 0; V <sub>CB</sub> = 20 V	_	_	100	nA
I <sub>EBO</sub>	emitter cut-off current	I <sub>C</sub> = 0; V <sub>EB</sub> = 4 V	_	-	100	nA
h <sub>FE</sub>	DC current gain	I <sub>C</sub> = 1 mA; V <sub>CE</sub> = 10 V	67	_	222	
$V_{BE}$	base-emitter voltage	I <sub>C</sub> = 1 mA; V <sub>CE</sub> = 10 V	675	725	775	mV
C <sub>re</sub>	feedback capacitance	I <sub>C</sub> = 0; V <sub>CB</sub> = 10 V; f = 1 MHz	-	0.3	_	pF
f <sub>T</sub>	transition frequency	I <sub>C</sub> = 1 mA; V <sub>CE</sub> = 10 V; f = 100 MHz	_	380	_	MHz

2004 Jan 13 3

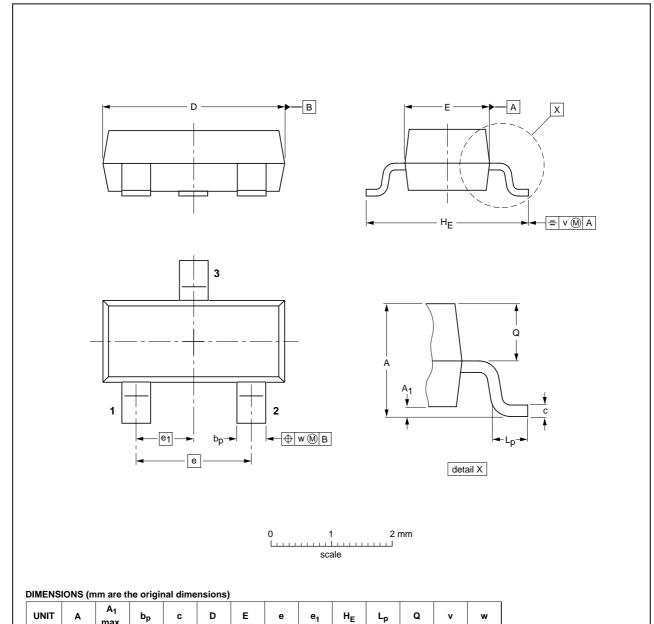
# NPN medium frequency transistor

BF840

#### **PACKAGE OUTLINE**

#### Plastic surface-mounted package; 3 leads

SOT23



OUTLINE	REFERENCES			EUROPEAN	ISSUE DATE	
VERSION	IEC JEDEC JEITA PROJECTION		ISSUE DATE			
SOT23		TO-236AB				<del>-04-11-04-</del> 06-03-16

0.45

0.55

0.1

2004 Jan 13 4

max

0.38

0.9

NXP Semiconductors Product data sheet

### NPN medium frequency transistor

BF840

#### **DATA SHEET STATUS**

DOCUMENT STATUS(1)	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

#### **Notes**

- 1. Please consult the most recently issued document before initiating or completing a design.
- 2. The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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2004 Jan 13 5

# **NXP Semiconductors**

#### **Customer notification**

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

#### **Contact information**

For additional information please visit: http://www.nxp.com
For sales offices addresses send e-mail to: salesaddresses@nxp.com

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